

L Number	Hits	Search Text	DB	Time stamp
6	39224	(substrate\$1 or wafer\$1 or workpiece\$1) and (photoresit or photosensitive) and (coat\$4 or layer\$4) and (exposur\$4 or radiat\$4 or irradiat\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/20 08:59
7	19889	((substrate\$1 or wafer\$1 or workpiece\$1) and (photoresit or photosensitive) and (coat\$4 or layer\$4) and (exposur\$4 or radiat\$4 or irradiat\$4)) and ((substrate\$1 or wafer\$1 or workpiece\$1) same (photoresit or photosensitive) same (coat\$4 or layer\$4)) and (exposur\$4 or radiat\$4 or irradiat\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/20 08:55
8	9647	((((substrate\$1 or wafer\$1 or workpiece\$1) and (photoresit or photosensitive) and (coat\$4 or layer\$4) and (exposur\$4 or radiat\$4 or irradiat\$4)) and ((substrate\$1 or wafer\$1 or workpiece\$1) same (photoresit or photosensitive) same (coat\$4 or layer\$4)) and (exposur\$4 or radiat\$4 or irradiat\$4)) and ((substrate\$1 or wafer\$1 or workpiece\$1) same (photoresit or photosensitive) same (coat\$4 or layer\$4) same (mask\$4 or pattern\$4)) and (exposur\$4 or radiat\$4 or irradiat\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/20 08:56
9	1764	(((((substrate\$1 or wafer\$1 or workpiece\$1) and (photoresit or photosensitive) and (coat\$4 or layer\$4) and (exposur\$4 or radiat\$4 or irradiat\$4)) and ((substrate\$1 or wafer\$1 or workpiece\$1) same (photoresit or photosensitive) same (coat\$4 or layer\$4)) and (exposur\$4 or radiat\$4 or irradiat\$4)) and ((substrate\$1 or wafer\$1 or workpiece\$1) same (photoresit or photosensitive) same (coat\$4 or layer\$4) same (mask\$4 or pattern\$4)) and (exposur\$4 or radiat\$4 or irradiat\$4)) and ((photoresit or photosensitive) same (coat\$4 or layer\$4) same (mask\$4 or pattern\$4) same (ink\$1 or liquid\$1 or fluid\$1)) and (exposur\$4 or radiat\$4 or irradiat\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/20 08:56
10	203	(((((substrate\$1 or wafer\$1 or workpiece\$1) and (photoresit or photosensitive) and (coat\$4 or layer\$4) and (exposur\$4 or radiat\$4 or irradiat\$4)) and ((substrate\$1 or wafer\$1 or workpiece\$1) same (photoresit or photosensitive) same (coat\$4 or layer\$4)) and (exposur\$4 or radiat\$4 or irradiat\$4)) and ((substrate\$1 or wafer\$1 or workpiece\$1) same (photoresit or photosensitive) same (coat\$4 or layer\$4) same (mask\$4 or pattern\$4)) and (exposur\$4 or radiat\$4 or irradiat\$4)) and ((photoresit or photosensitive) same (coat\$4 or layer\$4) same (mask\$4 or pattern\$4) same (ink\$1 or liquid\$1 or fluid\$1)) and (exposur\$4 or radiat\$4 or irradiat\$4)) and ((photoresit or photosensitive) same (coat\$4 or layer\$4) same (mask\$4 or pattern\$4) same ((ink\$1 or liquid\$1 or fluid\$1) with (jet\$4 or eject\$4 or spray\$4))) and (exposur\$4 or radiat\$4 or irradiat\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/20 08:58

11	119	<p>(((((substrate\$1 or wafer\$1 or workpiece\$1) and (photoresit or photosensitive) and (coat\$4 or layer\$4) and (exposur\$4 or radiat\$4 or irradiat\$4)) and ((substrate\$1 or wafer\$1 or workpiece\$1) same (photoresit or photosensitive) same (coat\$4 or layer\$4)) and (exposur\$4 or radiat\$4 or irradiat\$4)) and ((substrate\$1 or wafer\$1 or workpiece\$1) same (photoresit or photosensitive) same (coat\$4 or layer\$4) same (mask\$4 or pattern\$4)) and (exposur\$4 or radiat\$4 or irradiat\$4)) and ((photoresit or photosensitive) same (coat\$4 or layer\$4) same (mask\$4 or pattern\$4) same (ink\$1 or liquid\$1 or fluid\$1)) and (exposur\$4 or radiat\$4 or irradiat\$4)) and ((photoresit or photosensitive) same (coat\$4 or layer\$4) same (mask\$4 or pattern\$4) same ((ink\$1 or liquid\$1 or fluid\$1) with (jet\$4 or eject\$4 or spray\$4))) and (exposur\$4 or radiat\$4 or irradiat\$4)) and ((photoresit or photosensitive) same (coat\$4 or layer\$4) same ((mask\$4 or pattern\$4) with (ink\$1 or liquid\$1 or fluid\$1) with (jet\$4 or eject\$4 or spray\$4))) and (exposur\$4 or radiat\$4 or irradiat\$4))</p>	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/20 09:07
13	8	<p>(((((substrate\$1 or wafer\$1 or workpiece\$1) and (photoresit or photosensitive) and (coat\$4 or layer\$4) and (exposur\$4 or radiat\$4 or irradiat\$4)) and ((substrate\$1 or wafer\$1 or workpiece\$1) same (photoresit or photosensitive) same (coat\$4 or layer\$4)) and (exposur\$4 or radiat\$4 or irradiat\$4)) and ((substrate\$1 or wafer\$1 or workpiece\$1) same (photoresit or photosensitive) same (coat\$4 or layer\$4) same (mask\$4 or pattern\$4)) and (exposur\$4 or radiat\$4 or irradiat\$4)) and ((photoresit or photosensitive) same (coat\$4 or layer\$4) same (mask\$4 or pattern\$4) same (ink\$1 or liquid\$1 or fluid\$1)) and (exposur\$4 or radiat\$4 or irradiat\$4)) and ((photoresit or photosensitive) same (coat\$4 or layer\$4) same (mask\$4 or pattern\$4) same ((ink\$1 or liquid\$1 or fluid\$1) with (jet\$4 or eject\$4 or spray\$4))) and (exposur\$4 or radiat\$4 or irradiat\$4)) and ((photoresit or photosensitive) same (coat\$4 or layer\$4) same ((mask\$4 or pattern\$4) with (ink\$1 or liquid\$1 or fluid\$1) with (jet\$4 or eject\$4 or spray\$4))) and (exposur\$4 or radiat\$4 or irradiat\$4)) and ((photoresit or photosensitive) same (coat\$4 or layer\$4) same ((mask\$4 or pattern\$4) with (ink\$1 or liquid\$1 or fluid\$1) with (jet\$4 or eject\$4 or spray\$4)) same (exposur\$4 or radiat\$4 or irradiat\$4))) and ((substrate\$1 or wafer\$1 or workpiece\$1) same (rotat\$4 or circul\$4))</p>	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/20 09:00

12	77	(((((((substrate\$1 or wafer\$1 or workpiece\$1) and (photoresit or photosensitive) and (coat\$4 or layer\$4) and (exposur\$4 or radiat\$4 or irradiat\$4)) and ((substrate\$1 or wafer\$1 or workpiece\$1) same (photoresit or photosensitive) same (coat\$4 or layer\$4)) and (exposur\$4 or radiat\$4 or irradiat\$4)) and ((substrate\$1 or wafer\$1 or workpiece\$1) same (photoresit or photosensitive) same (coat\$4 or layer\$4) same (mask\$4 or pattern\$4)) and (exposur\$4 or radiat\$4 or irradiat\$4)) and ((photoresit or photosensitive) same (coat\$4 or layer\$4) same (mask\$4 or pattern\$4) same (ink\$1 or liquid\$1 or fluid\$1)) and (exposur\$4 or radiat\$4 or irradiat\$4)) and ((photoresit or photosensitive) same (coat\$4 or layer\$4) same (mask\$4 or pattern\$4) same ((ink\$1 or liquid\$1 or fluid\$1) with (jet\$4 or eject\$4 or spray\$4))) and (exposur\$4 or radiat\$4 or irradiat\$4)) and ((photoresit or photosensitive) same (coat\$4 or layer\$4) same ((mask\$4 or pattern\$4) with (ink\$1 or liquid\$1 or fluid\$1) with (jet\$4 or eject\$4 or spray\$4))) and (exposur\$4 or radiat\$4 or irradiat\$4)) and ((photoresit or photosensitive) same (coat\$4 or layer\$4) same ((mask\$4 or pattern\$4) with (ink\$1 or liquid\$1 or fluid\$1) with (jet\$4 or eject\$4 or spray\$4)) same (exposur\$4 or radiat\$4 or irradiat\$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/20 09:02
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14	42	<p> (((((((substrate\$1 or wafer\$1 or workpiece\$1) and (photoresit or photosensitive) and (coat\$4 or layer\$4) and (exposur\$4 or radiat\$4 or irradiat\$4)) and ((substrate\$1 or wafer\$1 or workpiece\$1) same (photoresit or photosensitive) same (coat\$4 or layer\$4)) and (exposur\$4 or radiat\$4 or irradiat\$4)) and ((substrate\$1 or wafer\$1 or workpiece\$1) same (photoresit or photosensitive) same (coat\$4 or layer\$4) same (mask\$4 or pattern\$4)) and (exposur\$4 or radiat\$4 or irradiat\$4)) and ((photoresit or photosensitive) same (coat\$4 or layer\$4) same (mask\$4 or pattern\$4) same (ink\$1 or liquid\$1 or fluid\$1)) and (exposur\$4 or radiat\$4 or irradiat\$4)) and ((photoresit or photosensitive) same (coat\$4 or layer\$4) same (mask\$4 or pattern\$4) same ((ink\$1 or liquid\$1 or fluid\$1) with (jet\$4 or eject\$4 or spray\$4))) and (exposur\$4 or radiat\$4 or irradiat\$4)) and ((photoresit or photosensitive) same (coat\$4 or layer\$4) same ((mask\$4 or pattern\$4) with (ink\$1 or liquid\$1 or fluid\$1) with (jet\$4 or eject\$4 or spray\$4))) and (exposur\$4 or radiat\$4 or irradiat\$4)) not </p> <p> (((((((substrate\$1 or wafer\$1 or workpiece\$1) and (photoresit or photosensitive) and (coat\$4 or layer\$4) and (exposur\$4 or radiat\$4 or irradiat\$4)) and ((substrate\$1 or wafer\$1 or workpiece\$1) same (photoresit or photosensitive) same (coat\$4 or layer\$4)) and (exposur\$4 or radiat\$4 or irradiat\$4)) and ((substrate\$1 or wafer\$1 or workpiece\$1) same (photoresit or photosensitive) same (coat\$4 or layer\$4) same (mask\$4 or pattern\$4)) and (exposur\$4 or radiat\$4 or irradiat\$4)) and ((photoresit or photosensitive) same (coat\$4 or layer\$4) same (mask\$4 or pattern\$4) same (ink\$1 or liquid\$1 or fluid\$1)) and (exposur\$4 or radiat\$4 or irradiat\$4)) and ((photoresit or photosensitive) same (coat\$4 or layer\$4) same (mask\$4 or pattern\$4) same ((ink\$1 or liquid\$1 or fluid\$1) with (jet\$4 or eject\$4 or spray\$4))) and (exposur\$4 or radiat\$4 or irradiat\$4)) and ((photoresit or photosensitive) same (coat\$4 or layer\$4) same ((mask\$4 or pattern\$4) with (ink\$1 or liquid\$1 or fluid\$1) with (jet\$4 or eject\$4 or spray\$4))) and (exposur\$4 or radiat\$4 or irradiat\$4)) and ((photoresit or photosensitive) same (coat\$4 or layer\$4) same ((mask\$4 or pattern\$4) with (ink\$1 or liquid\$1 or fluid\$1) with (jet\$4 or eject\$4 or spray\$4)) same (exposur\$4 or radiat\$4 or irradiat\$4))) </p>	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/20 09:12
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15	84	((((substrate\$1 or wafer\$1 or workpiece\$1) and (photoresit or photosensitive) and (coat\$4 or layer\$4) and (exposur\$4 or radiat\$4 or irradiat\$4)) and ((substrate\$1 or wafer\$1 or workpiece\$1) same (photoresit or photosensitive) same (coat\$4 or layer\$4)) and (exposur\$4 or radiat\$4 or irradiat\$4)) and ((substrate\$1 or wafer\$1 or workpiece\$1) same (photoresit or photosensitive) same (coat\$4 or layer\$4) same (mask\$4 or pattern\$4)) and (exposur\$4 or radiat\$4 or irradiat\$4)) and ((photoresit or photosensitive) same (coat\$4 or layer\$4) same (mask\$4 or pattern\$4) same (ink\$1 or liquid\$1 or fluid\$1)) and (exposur\$4 or radiat\$4 or irradiat\$4)) and ((photoresit or photosensitive) same (coat\$4 or layer\$4) same (mask\$4 or pattern\$4) same ((ink\$1 or liquid\$1 or fluid\$1) with (jet\$4 or eject\$4 or spray\$4))) and (exposur\$4 or radiat\$4 or irradiat\$4)) not ((((substrate\$1 or wafer\$1 or workpiece\$1) and (photoresit or photosensitive) and (coat\$4 or layer\$4) and (exposur\$4 or radiat\$4 or irradiat\$4)) and ((substrate\$1 or wafer\$1 or workpiece\$1) same (photoresit or photosensitive) same (coat\$4 or layer\$4)) and (exposur\$4 or radiat\$4 or irradiat\$4)) and ((substrate\$1 or wafer\$1 or workpiece\$1) same (photoresit or photosensitive) same (coat\$4 or layer\$4) same (mask\$4 or pattern\$4)) and (exposur\$4 or radiat\$4 or irradiat\$4)) and ((photoresit or photosensitive) same (coat\$4 or layer\$4) same (mask\$4 or pattern\$4) same (ink\$1 or liquid\$1 or fluid\$1)) and (exposur\$4 or radiat\$4 or irradiat\$4)) and ((photoresit or photosensitive) same (coat\$4 or layer\$4) same (mask\$4 or pattern\$4) same ((ink\$1 or liquid\$1 or fluid\$1) with (jet\$4 or eject\$4 or spray\$4))) and (exposur\$4 or radiat\$4 or irradiat\$4)) and ((photoresit or photosensitive) same (coat\$4 or layer\$4) same ((mask\$4 or pattern\$4) with (ink\$1 or liquid\$1 or fluid\$1) with (jet\$4 or eject\$4 or spray\$4))) and (exposur\$4 or radiat\$4 or irradiat\$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/20 09:12
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16	19	(((((((substrate\$1 or wafer\$1 or workpiece\$1) and (photoresit or photosensitive) and (coat\$4 or layer\$4) and (exposur\$4 or radiat\$4 or irradiat\$4)) and ((substrate\$1 or wafer\$1 or workpiece\$1) same (photoresit or photosensitive) same (coat\$4 or layer\$4)) and (exposur\$4 or radiat\$4 or irradiat\$4)) and ((substrate\$1 or wafer\$1 or workpiece\$1) same (photoresit or photosensitive) same (coat\$4 or layer\$4) same (mask\$4 or pattern\$4)) and (exposur\$4 or radiat\$4 or irradiat\$4)) and ((photoresit or photosensitive) same (coat\$4 or layer\$4) same (mask\$4 or pattern\$4) same (ink\$1 or liquid\$1 or fluid\$1)) and (exposur\$4 or radiat\$4 or irradiat\$4)) and ((photoresit or photosensitive) same (coat\$4 or layer\$4) same (mask\$4 or pattern\$4) same ((ink\$1 or liquid\$1 or fluid\$1) with (jet\$4 or eject\$4 or spray\$4))) and (exposur\$4 or radiat\$4 or irradiat\$4)) not (((((((substrate\$1 or wafer\$1 or workpiece\$1) and (photoresit or photosensitive) and (coat\$4 or layer\$4) and (exposur\$4 or radiat\$4 or irradiat\$4)) and ((substrate\$1 or wafer\$1 or workpiece\$1) same (photoresit or photosensitive) same (coat\$4 or layer\$4)) and (exposur\$4 or radiat\$4 or irradiat\$4)) and ((substrate\$1 or wafer\$1 or workpiece\$1) same (photoresit or photosensitive) same (coat\$4 or layer\$4) same (mask\$4 or pattern\$4)) and (exposur\$4 or radiat\$4 or irradiat\$4)) and ((photoresit or photosensitive) same (coat\$4 or layer\$4) same (mask\$4 or pattern\$4) same (ink\$1 or liquid\$1 or fluid\$1)) and (exposur\$4 or radiat\$4 or irradiat\$4)) and ((photoresit or photosensitive) same (coat\$4 or layer\$4) same (mask\$4 or pattern\$4) same ((ink\$1 or liquid\$1 or fluid\$1) with (jet\$4 or eject\$4 or spray\$4))) and (exposur\$4 or radiat\$4 or irradiat\$4)) and ((photoresit or photosensitive) same (coat\$4 or layer\$4) same ((mask\$4 or pattern\$4) with (ink\$1 or liquid\$1 or fluid\$1) with (jet\$4 or eject\$4 or spray\$4))) and (exposur\$4 or radiat\$4 or irradiat\$4))) and (rotat\$4 or circul\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/20 09:15
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17	65	<p> (((((((substrate\$1 or wafer\$1 or workpiece\$1) and (photoresit or photosensitive) and (coat\$4 or layer\$4) and (exposur\$4 or radiat\$4 or irradiat\$4)) and ((substrate\$1 or wafer\$1 or workpiece\$1) same (photoresit or photosensitive) same (coat\$4 or layer\$4)) and (exposur\$4 or radiat\$4 or irradiat\$4)) and ((substrate\$1 or wafer\$1 or workpiece\$1) same (photoresit or photosensitive) same (coat\$4 or layer\$4) same (mask\$4 or pattern\$4)) and (exposur\$4 or radiat\$4 or irradiat\$4)) and ((photoresit or photosensitive) same (coat\$4 or layer\$4) same (mask\$4 or pattern\$4) same (ink\$1 or liquid\$1 or fluid\$1)) and (exposur\$4 or radiat\$4 or irradiat\$4)) and ((photoresit or photosensitive) same (coat\$4 or layer\$4) same (mask\$4 or pattern\$4) same ((ink\$1 or liquid\$1 or fluid\$1) with (jet\$4 or eject\$4 or spray\$4))) and (exposur\$4 or radiat\$4 or irradiat\$4)) not </p> <p> (((((((substrate\$1 or wafer\$1 or workpiece\$1) and (photoresit or photosensitive) and (coat\$4 or layer\$4) and (exposur\$4 or radiat\$4 or irradiat\$4)) and ((substrate\$1 or wafer\$1 or workpiece\$1) same (photoresit or photosensitive) same (coat\$4 or layer\$4)) and (exposur\$4 or radiat\$4 or irradiat\$4)) and ((substrate\$1 or wafer\$1 or workpiece\$1) same (photoresit or photosensitive) same (coat\$4 or layer\$4) same (mask\$4 or pattern\$4)) and (exposur\$4 or radiat\$4 or irradiat\$4)) and ((photoresit or photosensitive) same (coat\$4 or layer\$4) same (mask\$4 or pattern\$4) same (ink\$1 or liquid\$1 or fluid\$1)) and (exposur\$4 or radiat\$4 or irradiat\$4)) and ((photoresit or photosensitive) same (coat\$4 or layer\$4) same (mask\$4 or pattern\$4) same ((ink\$1 or liquid\$1 or fluid\$1) with (jet\$4 or eject\$4 or spray\$4))) and (exposur\$4 or radiat\$4 or irradiat\$4)) and ((photoresit or photosensitive) same (coat\$4 or layer\$4) same ((mask\$4 or pattern\$4) with (ink\$1 or liquid\$1 or fluid\$1) with (jet\$4 or eject\$4 or spray\$4))) and (exposur\$4 or radiat\$4 or irradiat\$4))) not </p> <p> (((((((substrate\$1 or wafer\$1 or workpiece\$1) and (photoresit or photosensitive) and (coat\$4 or layer\$4) and (exposur\$4 or radiat\$4 or irradiat\$4)) and ((substrate\$1 or wafer\$1 or workpiece\$1) same (photoresit or photosensitive) same (coat\$4 or layer\$4)) and (exposur\$4 or radiat\$4 or irradiat\$4)) and ((substrate\$1 or wafer\$1 or workpiece\$1) same (photoresit or photosensitive) same (coat\$4 or layer\$4) same (mask\$4 or pattern\$4)) and (exposur\$4 or radiat\$4 or irradiat\$4)) and ((photoresit or photosensitive) same (coat\$4 or layer\$4) same (mask\$4 or pattern\$4) same (ink\$1 or liquid\$1 or fluid\$1)) and (exposur\$4 or radiat\$4 or irradiat\$4)) and ((photoresit or photosensitive) same (coat\$4 or layer\$4) same (mask\$4 or pattern\$4) same ((ink\$1 or liquid\$1 or fluid\$1) with (jet\$4 or eject\$4 or spray\$4))) and (exposur\$4 or radiat\$4 or irradiat\$4)) not </p>	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/20 09:16
Search History	9/20/2004 9:23:44 AM Page 7	(((((((substrate\$1 or wafer\$1 or workpiece\$1) and (photoresit or		